Sunday February 7th

F1: Silicon 3D-Integration Technology and Systems

Organizer: **Pascal Urard,** *STMicroelectronics, Crolles, France*

Co-organizer: **Ken Takeuchi,** *University of Tokyo, Tokyo, Japan*

Chair: **Kerry Bernstein,** *Applied Research Associates, South Royalton, VT*

Committee:
Hideto Hidaka, *Renesas Techonology, Itami, Japan*
Michael Phan, *Qualcomm, Raleigh, NC*
Joo Sun Choi, *Samsung Electronics, Hwasung, Korea*
Bob Payne, *Texas Instruments, Dallas, TX*
Vladimir Stojanovic, *MIT, Cambridge, MA*
Kees Van Berkel, *ST- Ericsson, Eindhoven, The Netherlands*
Takayasu Sakurai, *University of Tokyo, Tokyo, Japan*

This Forum brings together 3D-integration technologies (System-in-Package, Through-Silicon-Via, Contactless-Chip-to-Chip-Communication,...), key components (SDRAM, flash, SoC, sensor,...) and 3D applications (imagers, smart phones, solid-state disk drives,...).

Key issues addressed by the panel experts will include:
- -3D-integration standards
- -3D-integration technologies: SiP, Chip-Scale Packages, Bit-Cost-Scalable 3D cell stacking, TSV, contactless interfaces,...
- -Power issues, mechanical issues, temperature distribution
- -Product benefits and yields

And, finally, the panel will provide an answer to the question: When will 3D be ready for show time?

Forum Agenda

Time	Topic
8:00	Breakfast
8:20	**Introduction** **Pascal Urard,** *STMicroelectronics, Crolles, France*
8:30	**3D TSVs - Ready for Design!** **Pol Marchal,** *IMEC, Leuven, Belgium*
9:15	**3D for Wireless Mobile Multimedia Applications - Opportunities and Challenges** **Georg Kimmich,** *ST-Ericsson, Grenoble, France*
10:00	Break
10:15	**Chip-Scale Camera Module Using Through-Silicon-Via** **Jean-Luc Jaffard,** *STMicroelectronics, Grenoble, France*
11:00	**2.5D & 3D ICs: Solutions & Challenges** **Ho-Ming Tong,** *ASE Group, Kaoshiung, Taiwan*
11:45	**Contactless Interfaces in 3D-Integration** **Hiroki Ishikuro,** *Keio University, Yokohama, Japan*
12:30	Lunch
1:30	**Advancements in SiP Integration and Interconnect Technology** **Flynn Carson,** *STATS ChipPACK, Singapore*
2:15	**TSV Technology and its Application to DRAM** **Uksung Kang,** *Samsung, Korea*
3.00	Break
3:15	**3D Flash Memory Technology and Circuit Design** **Yoshihisa Iwata,** *Toshiba, Yokohama, Japan*
4:00	**3D Integration Challenges in Computing** **Samuel Naffziger,** *AMD, Fort Collins, CO*
4:10	Panel Discussion
5:10	Conclusion